



Product Change Notification - GBNG-07RHVT039

Date:

27 Mar 2018

Product Category:

Capacitive Touch Sensors; 8-bit PIC Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3179 Final Notice: Qualification of MMT as an additional assembly site for selected products of the 200K wafer technology available in 8L MSOP package using CuPdAu bond wire.

Notification text:**PCN Status:**

Final notification. **PCN**

Type: Manufacturing

Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 200K wafer technology available in 8L MSOP package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at MTAI assembly site.

Post Change:

Assembled at MTAI or MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand - HQ (MTAI)	Microchip Technology Thailand – Branch (MMT)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	8390A	8390A	8390A
Molding compound material	G600V	G600V	G600V
Lead frame material	CDA194	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress



Estimated First Ship Date:

April 20, 2018 (date code: 1816)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	November 2017					-->	March 2018					April 2018				
	44	45	46	47	48		09	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date					X											
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date													X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 28, 2017: Issued initial notification.

March 20, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on April 20, 2018.

March 27, 2018: Re-issued final notification to update the affected parts list.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-07RHVT039_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

MTCH102-I/MS
MTCH102T-I/MS
PIC12F1501-E/MS
PIC12F1501-E/MS031
PIC12F1501-I/MS
PIC12F1501T-E/MS
PIC12F1501T-E/MS036
PIC12F1501T-I/MS
PIC12F1571-E/MS
PIC12F1571-I/MS
PIC12F1571T-E/MS
PIC12F1571T-I/MS
PIC12F1572-E/MS
PIC12F1572-I/MS
PIC12F1572T-E/MS
PIC12F1572T-I/MS
PIC12LF1501-E/MS
PIC12LF1501-I/MS
PIC12LF1501T-E/MS
PIC12LF1501T-I/MS
PIC12LF1552-E/MS
PIC12LF1552-I/MS
PIC12LF1552T-E/MS
PIC12LF1552T-I/MS
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